

## MCH3321-VB Datasheet

# P-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
- 100	1.0 at V <sub>GS</sub> = - 10 V	- 0.52	7.7			
	1.05 at V <sub>GS</sub> = - 6.0 V	- 0.46	1.7			

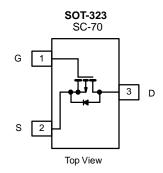
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- Trench Power MOSFET
- Ultra Low On-Resistance
- Small Size



#### **APPLICATIONS**

• Active Clamp Circuits in DC/DC Power Supplies



<b>ABSOLUTE MAXIMUM RATINGS</b>	T <sub>A</sub> = 25 °C, unle	ss otherwise r	noted			
Parameter	Symbol	5 s	Steady State	Unit		
Drain-Source Voltage		V <sub>DS</sub>	- 100		V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		V	
O(1	T <sub>A</sub> = 25 °C		- 0.52	- 0.43		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 70 °C	- I <sub>D</sub>	- 0.46	- 0.33		
Pulsed Drain Current		I <sub>DM</sub>	- 1.6		Α	
Continuous Source Current (Diode Conduction) <sup>a,</sup>	I <sub>S</sub>	- 0.8	- 0.5			
Single Pulse Avalanche Current		I <sub>AS</sub>	4.5			
Single Pulse Avalanche Energy	L = 1.0 mH	E <sub>AS</sub>	1.01		mJ	
Mariana Bana Birata di alb	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.05	0.65	W	
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C		0.55	0.38	VV	
Operating Junction and Storage Temperature Rar	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marrian In America	t ≤ 5 s	R <sub>thJA</sub>	75	100		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	' `thJA	120	166	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	40	50		

#### Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 100			V	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$			- 4.5	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zone Onto Valta va Bonio Over	1	V <sub>DS</sub> = - 150 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 150 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 1.6			Α	
5	D	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		1.0		0	
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 6.0 V, I <sub>D</sub> = - 0.5 A		1.05		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 0.5 A		2.2		S	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 1.0 A, V <sub>GS</sub> = 0 V		0.7	- 1.2	V	
Dynamic <sup>b</sup>	•		•	•			
Total Gate Charge	$Q_g$	V 75 V V 40 V		7.7	12	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -75 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} \cong -0.5 \text{ A}$		1.5			
Gate-Drain Charge	$Q_{gd}$	1D = - 0.0 A		2.5		•	
Gate Resistance	$R_g$	f = 1.0 MHz		9		Ω	
Input Capacitance	C <sub>iss</sub>			340	510		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		30		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			16			
Switching <sup>c</sup>	•		•	•			
Torre On Time	t <sub>d(on)</sub>	V 75.V.B 75.0		7	11		
Turn-On Time	t <sub>r</sub>	$V_{DD} = -75 \text{ V}, R_{L} = 75 \Omega$ $I_{D} \cong -1.0 \text{ A}, V_{GEN} = -10 \text{ V}$		11	17	ns	
Turn-Off Time	t <sub>d(off)</sub>	$R_{a} = 6 \Omega$		16	25	115	
Turn-On Time	t <sub>f</sub>	y = 3 ==		11	17		
Body Diode Reverse Recovery Charge Q <sub>rr</sub>		$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		90	135	nC	

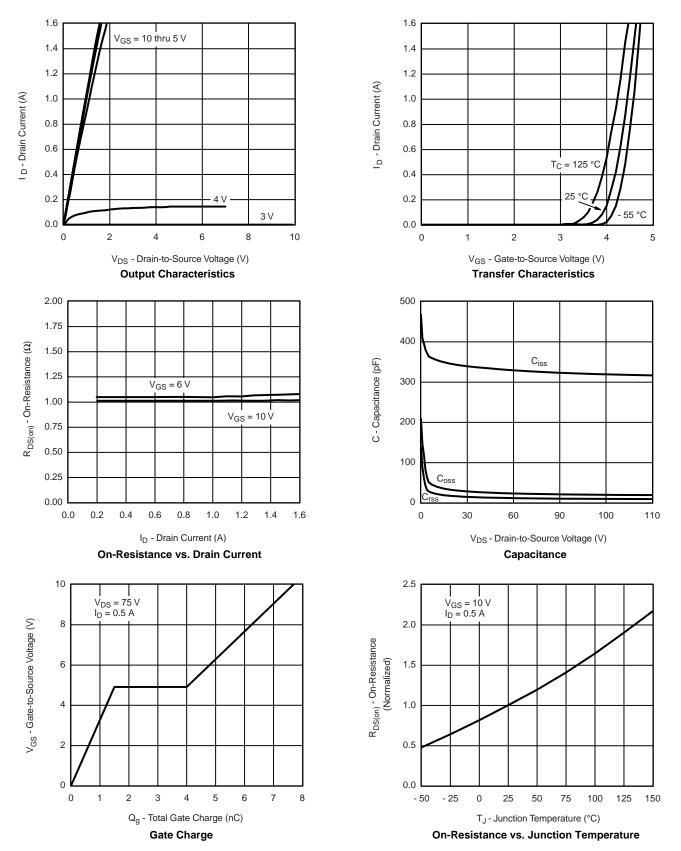
#### Notes:

- a. Pulse test: PW  $\leq 300~\mu s$  duty cycle  $\leq 2~\%.$
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

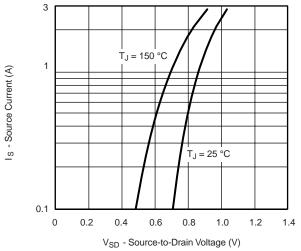


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

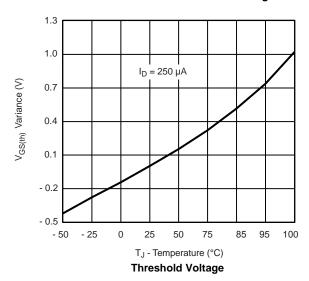


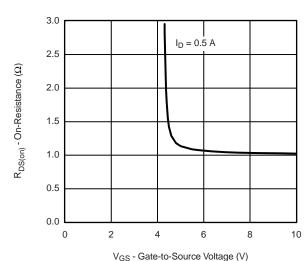


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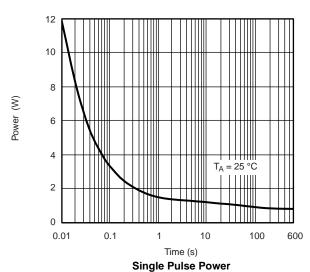


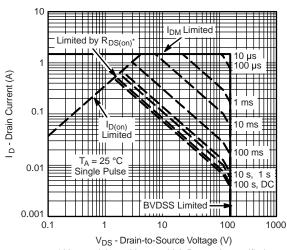
#### Source-Drain Diode Forward Voltage





#### On-Resistance vs. Gate-to-Source Voltage



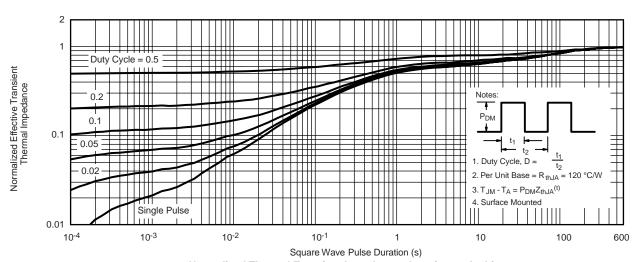


 $^*$  V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area



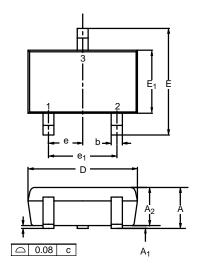
## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

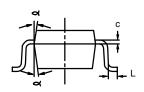


Normalized Thermal Transient Impedance, Junction-to-Ambient



## SC-70: 3-LEADS



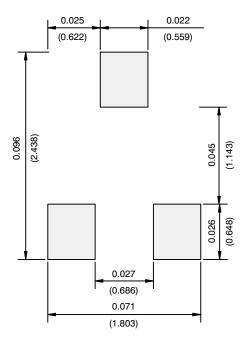


	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.90	-	1.10	0.035	-	0.043	
A <sub>1</sub>	_	_	0.10	-	_	0.004	
A <sub>2</sub>	0.80	_	1.00	0.031	_	0.039	
b	0.25	-	0.40	0.010	_	0.016	
С	0.10	-	0.25	0.004	-	0.010	
D	1.80	2.00	2.20	0.071	0.079	0.087	
Ε	1.80	2.10	2.40	0.071	0.083	0.094	
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65BSC			0.026BSC			
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055	
L	0.10	0.20	0.30	0.004	0.008	0.012	
ø	7°Nom 7°Nom						
ECN: S-03946—Rev. C, 09-Jul-01							

ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549



### **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)

服务热线:400-655-8788 Á 7



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